

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2997721

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	KENJI SUINA	07/26/2011
	TAKASHI ARAI	07/27/2011
	KOICHI MITA	07/26/2011
	AKIRA SHIMAMURA	07/27/2011
	HIDETOSHI ISHIKAWA	07/27/2011
	TAKASHI MORIYA	07/27/2011
	YUUKI NOZAWA	07/26/2011
	HIDEKI KONDO	07/26/2011
RECEIVING PARTY DATA		
Name:	FUJITSU SEMICONDUCTOR LIMITED	
Street Address:	2-10-23 SHIN-YOKOHAMA,	
Internal Address:	KOHOKU-KU, YOKOHAMA-SHI	
City:	KANAGAWA	
State/Country:	JAPAN	
Postal Code:	222-0033	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14221011	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Email:	mlee@skgf.com, pdykstra@skgf.com, bthompson@skgf.com	
Correspondent Name:	STERNE, KESSLER, GOLDSTEIN & FOX PLLC	
Address Line 1:	1100 NEW YORK AVENUE	
Address Line 4:	WASHINGTON, D.C. 20005	
ATTORNEY DOCKET NUMBER:	5186.5340002	
NAME OF SUBMITTER:	MICHAEL Q. LEE	
SIGNATURE:	/Michael Q. Lee#35,239/	
DATE SIGNED:	08/26/2014	

PATENT

Total Attachments: 2

source=Assignment1#page1.tif

source=Assignment1#page2.tif

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by
(Insert Name(s) & Address(es) of ASSIGNEE(S))

Fujitsu Semiconductor Limited

2-10-23 Shin-Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa 222-0033 Japan

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled
(Title of Invention)

NODE SYSTEM AND SUPERVISORY NODE

relating to International Patent Application PCT/JP_____/_____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on _____;

(Insert date of execution of application, if not concurrent)

(b) filed on August 26, 2011;

Serial No. 13/ 219,211;

Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

1) Kenji Suina
(Signature)

Kenji SUINA
(Type Name)

July, 26, 2011
(Date)

2) 新井 隆
(Signature)

Takashi ARAI
(Type Name)

July, 27, 2011
(Date)

3) 三田 浩一
(Signature)

Koichi MITA
(Type Name)

July, 26, 2011
(Date)

4) 島村 章
(Signature)

Akira SHIMAMURA
(Type Name)

July, 27, 2011
(Date)

PATENT
REEL: 026823 FRAME: 0862

PATENT
REEL: 033613 FRAME: 0231

5)	<u>石川 英利</u> (Signature)	<u>Hidetoshi ISHIKAWA</u> (Type Name)	<u>July. 27, 2011</u> (Date)
6)	<u>安屋 聖</u> (Signature)	<u>Takashi MORIYA</u> (Type Name)	<u>July. 27, 2011</u> (Date)
7)	<u>Yuuki Nozawa</u> (Signature)	<u>Yuuki NOZAWA</u> (Type Name)	<u>July. 26, 2011</u> (Date)
8)	<u>近藤 秀輝</u> (Signature)	<u>Hideki KONDO</u> (Type Name)	<u>July. 26, 2011</u> (Date)

RECORDED: 08/29/2011

PATENT
REEL: 026823 FRAME: 0863

RECORDED: 08/26/2014

PATENT
REEL: 033613 FRAME: 0232